

Automotive Dual N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY	1
V _{DS} (V)	60
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0562
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0745
I _D (A) per leg	15
Configuration	Dual
Package	PowerPAK SO-8L

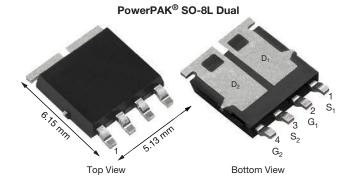
FEATURES

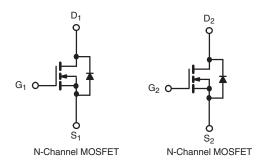
- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





ROHS COMPLIANT HALOGEN FREE





ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unless	s otherwise noted	l)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	60		
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current a	T _C = 25 °C	1	15		
Continuous Drain Current 4	T _C = 125 °C	l _D	10.5		
Continuous Source Current (Diode conduction) ^a		Is	8	Α	
Pulsed Drain Current ^b		I _{DM}	60		
Single Pulse Avalanche Current		I _{AS}	16		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	12	mJ	
Maximum Dawar Dissination h	T _C = 25 °C	D	34	10/	
Maximum Power Dissipation ^b	T _C = 125 °C	P_{D}	11	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	%C	
Soldering Recommendations (Peak temperature) d, e		-	260	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB mount c	R _{thJA}	85	°C/W
Junction-to-Case (Drain)		R _{thJC}	4.3	G/VV

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						L	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	60	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.5	2.0	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μΑ
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	20	-	-	Α
		V _{GS} = 10 V	I _D = 3.7 A	-	0.0470	0.0562	
Dunin Course On Chata Basistana 3		V _{GS} = 10 V	I _D = 3.7 A, T _J = 125 °C	-	-	0.0989	Ω
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.7 A, T _J = 175 °C	-	-	0.1254	
		V _{GS} = 4.5 V	I _D = 3.3 A	-	0.0620	0.0745	
Forward Transconductance b	g _{fs}	V _{DS} = 15 V, I _D = 5 A		-	11	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			=	357	446	
Output Capacitance	Coss	$V_{GS} = 0 V$	$V_{GS} = 0 \text{ V}$ $V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}$		66	83	pF
Reverse Transfer Capacitance	C _{rss}			=.	26	33	
Total Gate Charge ^c	Qg			=.	8.1	12	
Gate-Source Charge c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 4.5 \text{ A}$	-	1.3	-	nC
Gate-Drain Charge ^c	Q _{gd}			-	1.7	-	
Gate Resistance	R_g	f = 1 MHz		1.1	-	7	Ω
Turn-On Delay Time ^c	t _{d(on)}				6	9	- ns
Rise Time ^c	t _r	$V_{DD}=30~V,~R_L=30~\Omega$ $I_D\cong 1~A,~V_{GEN}=10~V,~R_g=1~\Omega$		-	6	9	
Turn-Off Delay Time ^c	t _{d(off)}			=.	12	18	
Fall Time ^c	t _f			-	7	11	
Source-Drain Diode Ratings and Chara	icteristics ^b						
Pulsed Current ^a	I _{SM}			-	-	60	Α
Forward Voltage	V _{SD}	I _F =	2.4 A, V _{GS} = 0 V	-	0.8	1.1	V

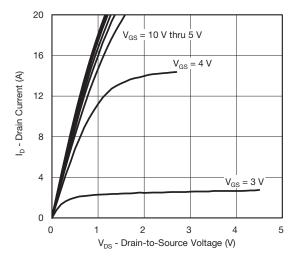
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

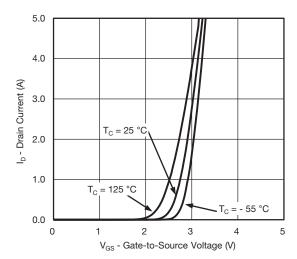
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



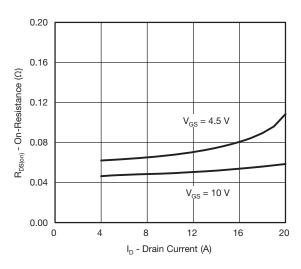
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



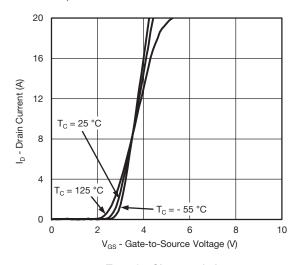
Output Characteristics



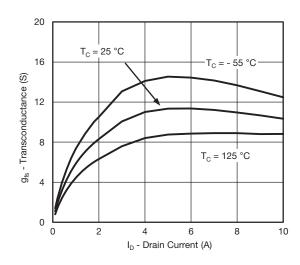
Transfer Characteristics



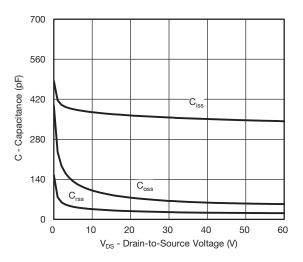
On-Resistance vs. Drain Current



Transfer Characteristics

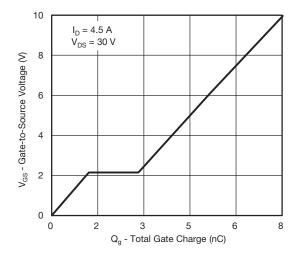


Transconductance

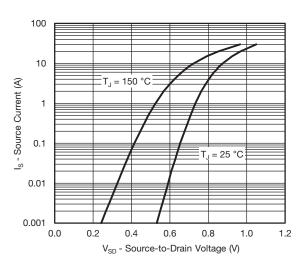




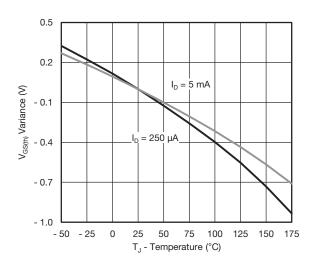
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



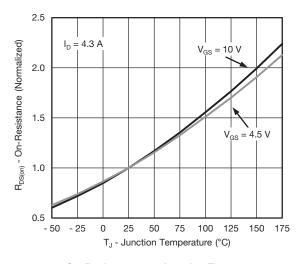
Gate Charge



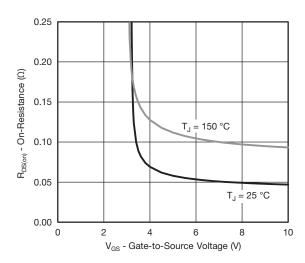
Source Drain Diode Forward Voltage



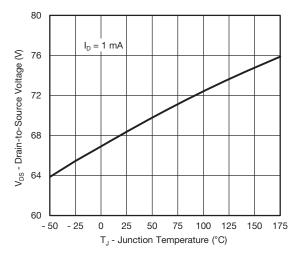
Threshold Voltage



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

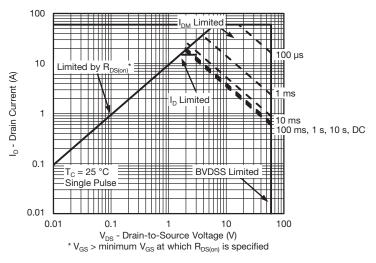


Drain Source Breakdown vs. Junction Temperature

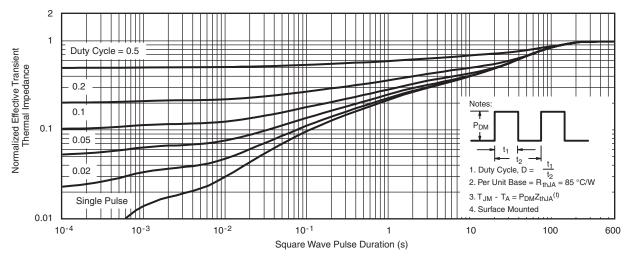
For technical questions, contact: automostechsu



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



Safe Operating Area

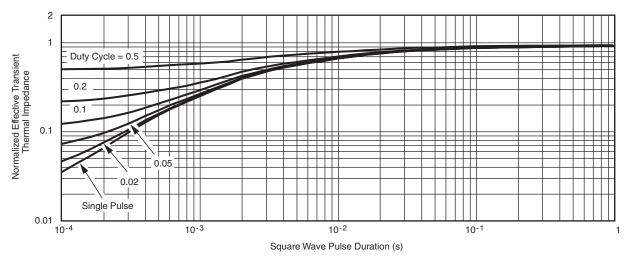


Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

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Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63267.





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REVISION	HISTORY a		
REVISION	DATE	DESCRIPTION OF CHANGE	
В	04-Aug-15	Revised R _g minimum limit	
С	14-Jun-16	Corrected I _D in product summary table	

Note

a. As of April 2014

PowerPAK® SO-8L

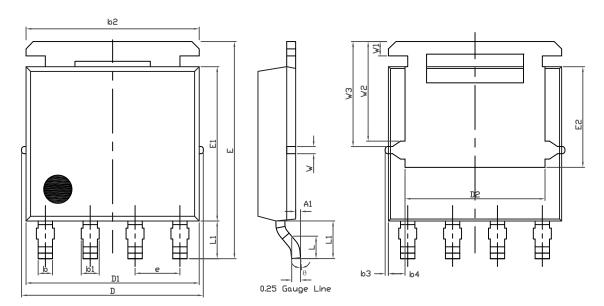
Ordering codes for the SQ rugged series power MOSFETs in the PowerPAK SO-8L package:

DATASHEET PART NUMBER	OLD ORDERING CODE ^a	NEW ORDERING CODE
SQJ200EP	-	SQJ200EP-T1_GE3
SQJ202EP	-	SQJ202EP-T1_GE3
SQJ401EP	SQJ401EP-T1-GE3	SQJ401EP-T1_GE3
SQJ402EP	SQJ402EP-T1-GE3	SQJ402EP-T1_GE3
SQJ403EEP	SQJ403EEP-T1-GE3	SQJ403EEP-T1_GE3
SQJ403EP	-	SQJ403EP-T1_GE3
SQJ410EP	SQJ410EP-T1-GE3	SQJ410EP-T1_GE3
SQJ412EP	SQJ412EP-T1-GE3	SQJ412EP-T1_GE3
SQJ416EP	-	SQJ416EP-T1_GE3
SQJ418EP	-	SQJ418EP-T1_GE3
SQJ422EP	SQJ422EP-T1-GE3	SQJ422EP-T1 GE3
SQJ423EP	-	SQJ423EP-T1_GE3
SQJ431EP	SQJ431EP-T1-GE3	SQJ431EP-T1_GE3
SQJ443EP	SQJ443EP-T1-GE3	SQJ443EP-T1_GE3
SQJ444EP	-	SQJ444EP-T1_GE3
SQJ446EP	-	SQJ446EP-T1 GE3
SQJ456EP	SQJ456EP-T1-GE3	SQJ456EP-T1 GE3
SQJ457EP	-	SQJ457EP-T1_GE3
SQJ459EP		SQJ459EP-T1_GE3
SQJ460AEP		SQJ460AEP-T1 GE3
	SQJ461EP-T1-GE3	SQJ461EP-T1 GE3
SQJ461EP	SQJ463EP-T1-GE3	
SQJ463EP		SQJ463EP-T1_GE3
SQJ465EP	SQJ465EP-T1-GE3	SQJ465EP-T1_GE3
SQJ469EP	SQJ469EP-T1-GE3	SQJ469EP-T1_GE3
SQJ474EP	<u>-</u>	SQJ474EP-T1_GE3
SQJ476EP	-	SQJ476EP-T1_GE3
SQJ479EP	-	SQJ479EP-T1_GE3
SQJ486EP	SQJ486EP-T1-GE3	SQJ486EP-T1_GE3
SQJ488EP	SQJ488EP-T1-GE3	SQJ488EP-T1_GE3
SQJ500AEP	SQJ500AEP-T1-GE3	SQJ500AEP-T1_GE3
SQJ840EP	SQJ840EP-T1-GE3	SQJ840EP-T1_GE3
SQJ844AEP	SQJ844AEP-T1-GE3	SQJ844AEP-T1_GE3
SQJ850EP	SQJ850EP-T1-GE3	SQJ850EP-T1_GE3
SQJ858AEP	SQJ858AEP-T1-GE3	SQJ858AEP-T1_GE3
SQJ868EP	-	SQJ868EP-T1_GE3
SQJ886EP	SQJ886EP-T1-GE3	SQJ886EP-T1_GE3
SQJ910AEP	SQJ910AEP-T1-GE3	SQJ910AEP-T1_GE3
SQJ912AEP	SQJ912AEP-T1-GE3	SQJ912AEP-T1_GE3
SQJ940EP	SQJ940EP-T1-GE3	SQJ940EP-T1_GE3
SQJ942EP	SQJ942EP-T1-GE3	SQJ942EP-T1_GE3
SQJ951EP	SQJ951EP-T1-GE3	SQJ951EP-T1_GE3
SQJ952EP	-	SQJ952EP-T1_GE3
SQJ956EP	SQJ956EP-T1-GE3	SQJ956EP-T1_GE3
SQJ960EP	SQJ960EP-T1-GE3	SQJ960EP-T1_GE3
SQJ963EP	SQJ963EP-T1-GE3	SQJ963EP-T1_GE3
SQJ968EP	SQJ968EP-T1-GE3	SQJ968EP-T1_GE3
SQJ980AEP	SQJ980AEP-T1-GE3	SQJ980AEP-T1_GE3
SQJ992EP	SQJ992EP-T1-GE3	SQJ992EP-T1_GE3

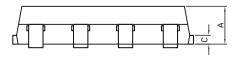
Note

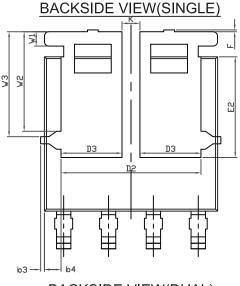
a. Old ordering code is obsolete and no longer valid for new orders

PowerPAK® SO-8L Case Outline for Al Parts



TOPSIDE VIEW





BACKSIDE VIEW(DUAL)



DIM	MILLIMETERS			INCHES			
DIM.	MIN. NOM. MAX.		MAX.	MIN. NOM. MAX			
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W		0.23			0.009		
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
q	0°	-	10°	0°	-	10°	

ECN: C15-1203-Rev. A, 07-Sep-15

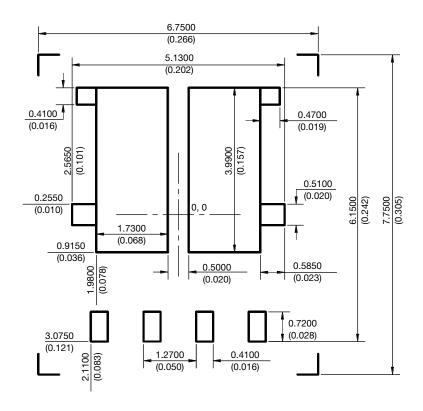
DWG: 6044

Note

· Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)



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